



A96AB 導熱封膠

Epoxy Potting Compound

REACH Compliant

RoHS Compliant

產品特性 Features

- 環氧樹脂材料，高硬度可用於支撐
Epoxy based material with high hardness for support
- 固化後保護電子元件防止受外界環境影響
Protect components from any effect after curing
- 可用點膠機灌注
Can be applied with dispenser
- 室溫或加熱熱化
Room temperature or heating curing

產品應用端 Applications

電子元件 Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED, Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device, Wireless Hub, DDR II Module, etc.

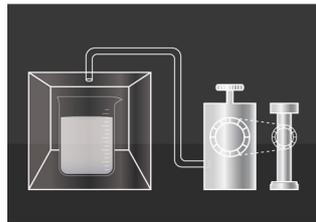
保存方式 Storage

導熱封膠其在未開封之狀態，在室溫 25° C 以下可保存 12 個月。
Epoxy Potting Compound has a shelf-life of twelve (12) months from the date of manufacture, as indicated by the lot number, when stored in the original, unopened contained at or below 25° C.

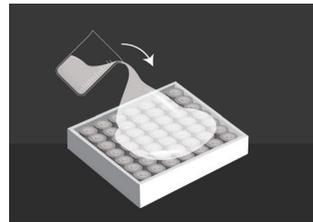
操作說明 Operation Manual



① Mix component A and B.



② Vacuum out air.



③ Pour potting compound.

產品物性 Properties

導熱係數 Thermal Conductivity : 2.6 W/mK

硬度 Hardness : 68 (Shore A)

0 0.8 1.2 1.4 1.6 1.7 1.8 2.2 3.2 3.6 4.0 4.5 5.0 15 20



0 5 10 15 20 25 30 40 80



Properties	A96AB	Unit	Tolerance	Test Method
導熱係數 Thermal Conductivity	2.6	W/mK	±0.25	ASTM D5470
顏色 Color	白 White/ 黑 Black	-	-	目視 Visual
耐電壓 Dielectric Breakdown Voltage	10.2	KV/mm	±1	ASTM D149
重量損失 Weight Loss	<1	%	-	ASTM E595
密度 Density	1.8	g/cm ³	±0.2	ASTM D792
工作溫度 Working Temperature	-25~+150	°C	-	-
黏度 Viscosity	1800~2500	cps	-	ASTM D2393
固化時間 Curing Time @25° C	35	Hrs	-	-
固化時間 Curing Time @80° C	1.5	Hrs	-	-
標準規格 Standard Format	1kg	Pot	-	-
硬度 Hardness	68	Shore A	±8	ASTM D2240
混合比例 Mixing Ratio	13:1	gram	-	-

- ▶ A 劑為 epoxy 與導熱粉混合材料，因密度不同會造成沉澱分層，屬正常現象，使用前請用扁平刮刀或是其他不鏽鋼工具，均勻攪拌 A 劑，以獲得最好的導熱效果。
Component A is a mixed material of epoxy and thermal conductive powder. It is normal to cause precipitation and stratification due to different density. Before use, please use a flat spatula or other stainless tools to evenly mix component A to achieve the best thermal conductivity.